

IN THE CLAIMS:

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1-14 (Canceled)

15. (Currently Amended) A method of manufacturing a light emitting device, comprising:
forming a ~~first~~ sealing material so as to surround at least a light emitting element over an insulator;
adhering a covering material to said insulator by said ~~first~~ sealing material;
cutting a first part of said insulator and a first part of said covering material after said step of adhering said covering material;
injecting an encapsulant in a portion surrounded by said insulator, said covering material, and said ~~first~~ sealing material; and
cutting a second part of said insulator and a second part of said covering material after said step of injecting said encapsulant.

16. (Currently Amended) A method according to claim 15, further comprising scattering a spacer over the insulator before or after the ~~first~~ sealing material is formed.

17. (Original) A method according to claim 15, wherein the encapsulant comprises a resin.

18. (Original) A method according to claim 15, wherein a hygroscopic substance is added to the encapsulant.

19. (Previously Presented) A method of manufacturing a light emitting device, comprising:
forming a first sealing material so as to surround at least a light emitting element over an insulator;
adhering a covering material to said insulator by said first sealing material;
cutting a first part of said insulator and a first part of said covering material after said step of adhering said covering material;
injecting an encapsulant in a portion surrounded by said insulator, said covering material, and said first sealing material;
cutting a second part of said insulator and a second part of said covering material after said step of injecting said encapsulant;
attaching a connecting terminal over said insulator; and
forming a second sealing material so as to abut an exposed portion of said first sealing material and a part of said connecting terminal.

20. (Previously Presented) A method according to claim 19, further comprising scattering a spacer over the insulator before or after the first sealing material is formed.

21. (Original) A method according to claim 19, wherein the encapsulant comprises a resin.

22. (Original) A method according to claim 19, wherein a hygroscopic substance is added to the encapsulant.

23. (Currently Amended) A method of manufacturing a light emitting device, comprising:

forming a ~~first~~ sealing material so as to surround at least a light emitting element over an insulator;

dropping encapsulant over said light emitting element;

adhering a covering material to said insulator by said ~~first~~ sealing material after said step of dropping said encapsulant, wherein the cover material is in contact with the sealing material; and

cutting a part of said insulator and a part of said covering material after said step of adhering said covering material.

24. (Currently Amended) A method according to claim 23, further comprising scattering a spacer over the insulator before or after the ~~first~~ sealing material is formed.

25. (Original) A method according to claim 23, wherein the encapsulant comprises a resin.

26. (Original) A method according to claim 23, wherein a hygroscopic substance is added to the encapsulant.

27. (Currently Amended) A method of manufacturing a light emitting device, comprising:
forming a first sealing material so as to surround at least a light emitting element over a surface of a substrate;

dropping encapsulant over said light emitting element;

adhering a covering material to said substrate by said first sealing material after said step of dropping said encapsulant, wherein the cover material is in contact with the first sealing material;

cutting a part of said substrate and a part of said covering material after said step of adhering

said covering material;

attaching a connecting terminal over said substrate; and

forming a second sealing material so as to abut an exposed portion of said first sealing material and a part of said connecting terminal.

28. (Previously Presented) A method according to claim 27, further comprising scattering a spacer over the insulator before or after the first sealing material is formed.

29. (Original) A method according to claim 27, wherein the encapsulant comprises a resin.

30. (Original) A method according to claim 27, wherein a hygroscopic substance is added to the encapsulant.